

L Number	Hits	Search Text	DB	Time stamp
1	116541	gasket polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:01
2	25	(gasket polytetrafluorethylene) same lossy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:01
3	2858366	(semiconductor processor microprocessor chip die ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:03
4	430180	heat with (dissipate sink spreader slug element metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:04
5	420607	eds electrostatic electro-static (electro adj3 static)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:05
6	26672	(eds electrostatic electro-static (electro adj3 static)) with (discharge discharging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:05
7	503	(gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:05
8	44	(gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:24
9	459	((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))) not ((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:24

10	127	(((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))) not ((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging)))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/19 05:24
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